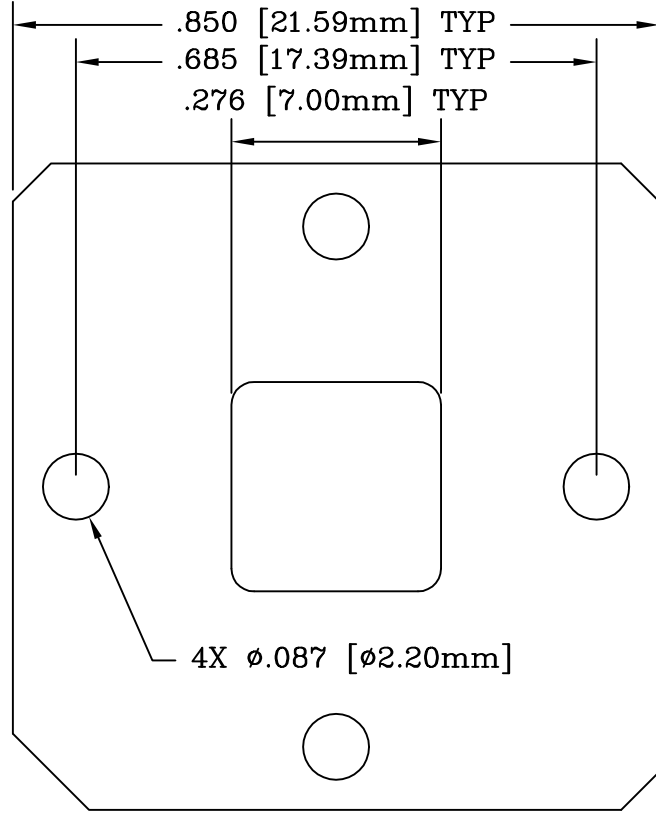
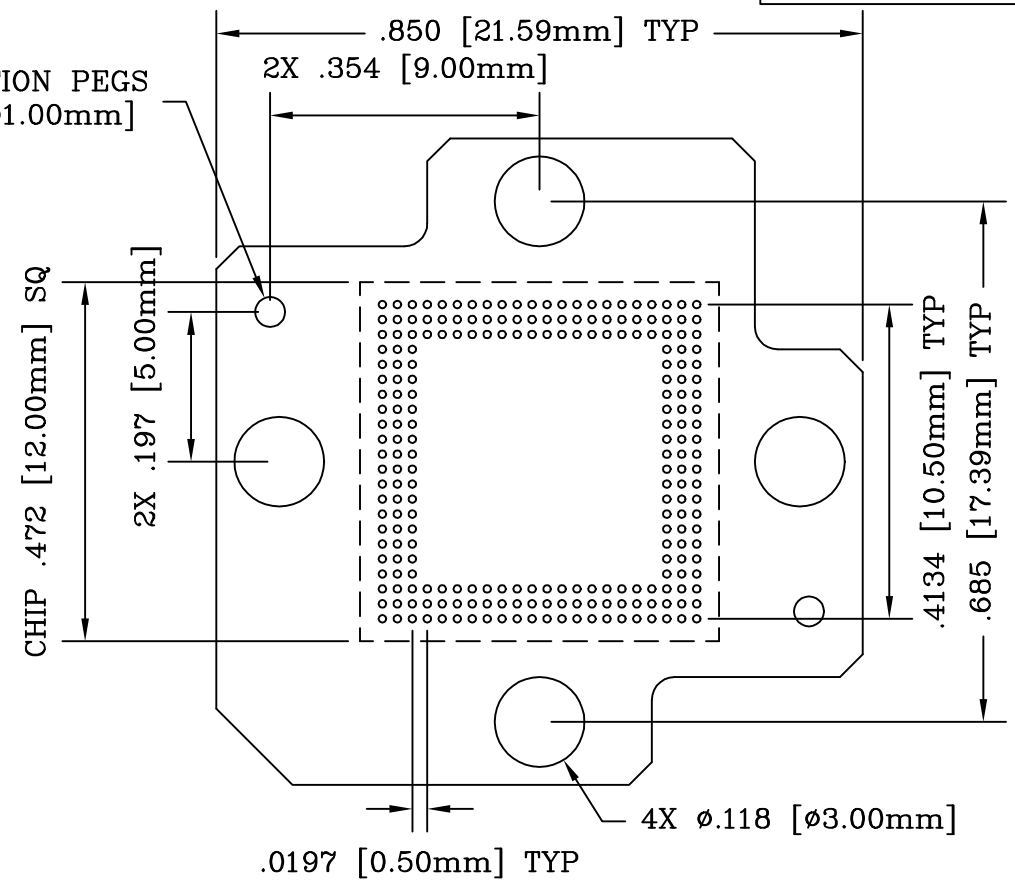


| REV | DESCRIPTION | DATE | BY |
|-----|-------------|----------|------|
| A | NEW DRAWING | 06/03/03 | H.N. |

SKT1760
DOD 41760



2X LOCATION PEGS
Ø.039 [Ø1.00mm]



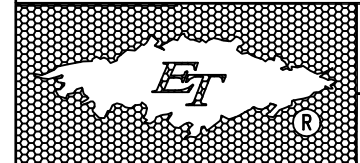
RECOMMENDED PAD LAYOUT

| SOLDERTAIL STYLE | | SOLDERTAIL = THRU HOLE STYLE | |
|---|--|--|--|
| REGULAR SMT STYLE XX = (-SM) YY = (-30) | RAISED SMT STYLE XX = (-RC) YY = (-29) | XX = (-ET) YY = (-70) | |
| <p>Pitch(PCB) * A PCB Layout Ø.0118 [Ø0.30mm]</p> | | <p>Pitch(PCB) * A PCB Layout Ø.0138 [Ø0.35mm]</p> | |
| <p>-30= standard SMT ("A" = .0157 [0.40mm]) -29= raised SMT ("A" = .091 [2.30mm])</p> | | <p>PIN DIAMETER FOR: -30(SM) = .0098 [0.25mm] TO .0138 [0.35mm] -29(RC) = .0098 [0.25mm] TO .0138 [0.35mm]</p> | |
| <p>BALL HEIGHT FOR: -30(SM) = .0059 [0.15mm] TO .0118 [0.30mm] -29(RC) = .0059 [0.15mm] TO .0118 [0.30mm]</p> | | <p>PIN DIAMETER FOR: -70(ET) = .0098 [0.25mm]</p> | |

PACKAGE SPECIFICATIONS

| | |
|--------------|--------------|
| PIN COUNT | = 228 |
| LEAD PITCH | = 0.50mm |
| GRID SIZE | = 22X22 |
| PACKAGE SIZE | = 12.00mm SQ |

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.
— VLSI and SMT ADAPTERS and ACCESSORIES —
2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
TEL:(408)982-0660 FAX:(408)982-0664

| | | | |
|--------------------------|----------------------|--------------------------|-----------------------------------|
| SHEET: 1 OF 1 | DATE: 06/03/03 | REVISION: A | ASSEMBLY DRAWING |
| CHECKED: Perry Munroe | DRAWN: Huy Nguyen | ITEM: S-MBG-22-228-XX | DESCRIPTION: BPW-228-5BG022-YY |
| Scale 4:1 | DO NOT SCALE DRAWING | | |

* All Dimmensions Are Nominal For A .0197 [0.50mm] Pitch BGA Package